

ABSTRACT

Side braze packages for semiconductor devices are disclosed. A disclosed side braze package includes a lead located at a sidewall of a main body having a groove. A first semiconductor chip is flip chip bonded on the groove through a solder bump. A second semiconductor chip is stacked on the first semiconductor chip. A first through hole is formed from an upper portion of the main body to a lower portion of the main body around an inner sidewall of the groove. A first line is connected to the lead through the solder bump and the first through hole. A second line is connected to the lead through the first through hole. A wire interconnects a pad of the second semiconductor to the second line.